



3.3V CMOS 10-BIT BUFFER

IDT74FCT3827A/B

FEATURES:

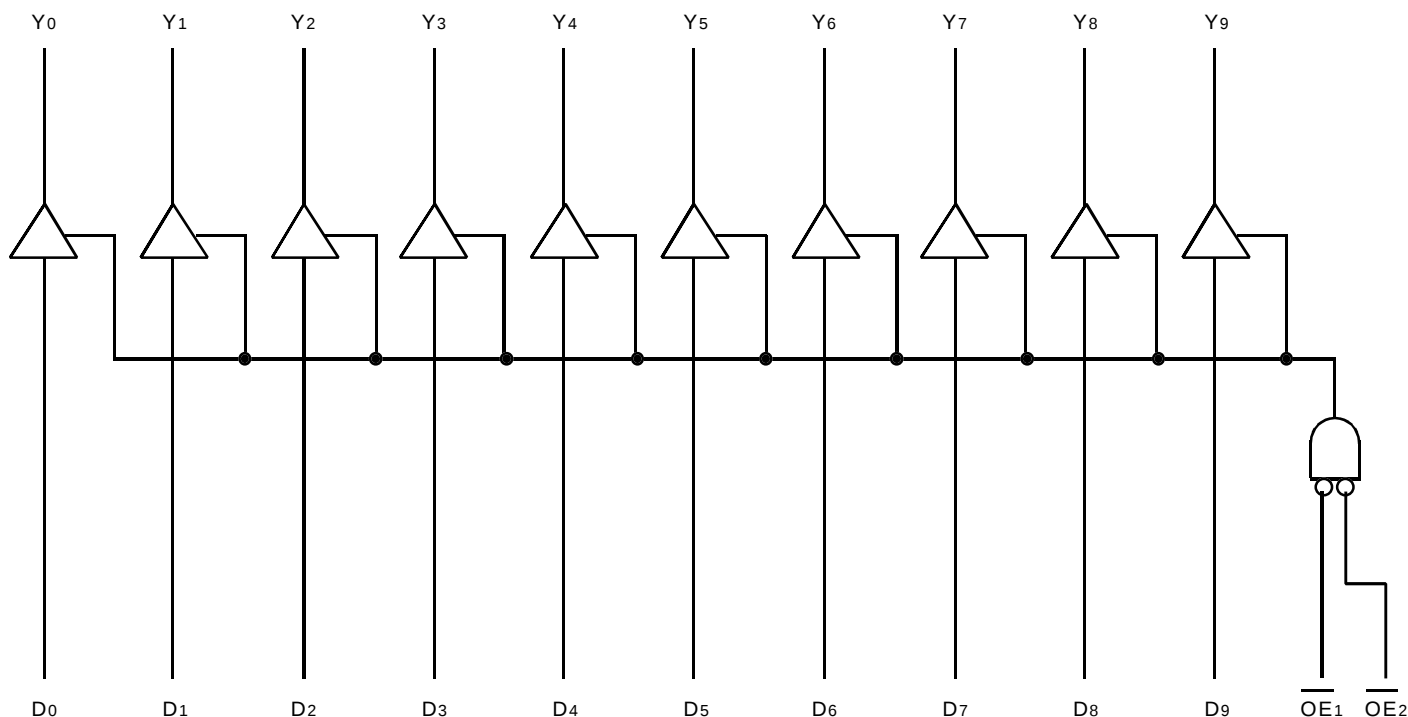
- 0.5 MICRON CMOS Technology
- ESD > 2000V per MIL-STD-883, Method 3015; > 200V using machine model (C = 200pF, R = 0)
- $V_{CC} = 3.3V \pm 0.3V$, Normal Range
- $V_{CC} = 2.7V$ to $3.6V$, Extended Range
- CMOS power levels ($0.4\mu W$ typ. static)
- Rail-to-Rail output swing for increased noise margin

DESCRIPTION:

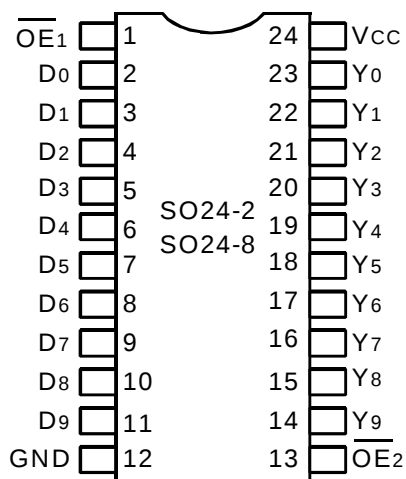
The FCT3827A/B 10-bit bus drivers are built using an advanced dual metal CMOS technology. These high speed, low power buffers are ideal for high-performance bus interface buffering for wide data/address paths or buses carrying parity. The 10-bit buffers have NAND-ed output enables for maximum control flexibility.

All of the FCT3827 high performance interface components are designed for high-capacitance load drive capability, while providing low-capacitance bus loading at both inputs and outputs.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION



SOIC/ QSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to +7	V
VTERM ⁽⁴⁾	Terminal Voltage with Respect to GND	-0.5 to VCC+0.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-60 to +60	mA

3V-8-link

NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- VCC terminals.
- Input terminals.
- Outputs and I/O terminals.

CAPACITANCE (TA = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	3.5	6	pF
COUT	Output Capacitance	VOUT = 0V	4	8	pF

3V-8-link

NOTE:

- This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Names	I/O	Description
OE1	I	When both are LOW the outputs are enabled. When either one or both are HIGH the outputs are High Z.
DI	I	10-bit data input.
YI	O	10-bit data output.

FUNCTION TABLE (1)

Inputs			Outputs	Function
OE1	OE2	DI	YI	
L	L	L	L	Transparent
L	L	H	H	
H	X	X	Z	Three-State
X	H	X	Z	

NOTE:

- H = HIGH Voltage Level
X = Don't Care
L = LOW Voltage Level
Z = High-Impedance

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Industrial: $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{CC} = 2.7\text{V}$ to 3.6V

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
V_{IH}	Input HIGH Level (Input pins)	Guaranteed Logic HIGH Level		2	—	5.5	V
	Input HIGH Level (I/O pins)			2	—	$V_{CC}+0.5$	
V_{IL}	Input LOW Level (Input and I/O pins)	Guaranteed Logic LOW Level		-0.5	—	0.8	V
I_{IH}	Input HIGH Current (Input pins)	$V_{CC} = \text{Max.}$	$V_I = 5.5\text{V}$	—	—	± 1	μA
	Input HIGH Current (I/O pins)		$V_I = V_{CC}$	—	—	± 1	
I_{IL}	Input LOW Current (Input pins)		$V_I = \text{GND}$	—	—	± 1	
	Input LOW Current (I/O pins)		$V_I = \text{GND}$	—	—	± 1	
I_{OZH}	High Impedance Output Current (3-State Output pins)	$V_{CC} = \text{Max.}$	$V_O = V_{CC}$	—	—	± 1	μA
I_{OZL}			$V_O = \text{GND}$	—	—	± 1	
V_{IK}	Clamp Diode Voltage	$V_{CC} = \text{Min.}, I_{IN} = -18\text{mA}$		—	-0.7	-1.2	V
I_{ODH}	Output HIGH Current	$V_{CC} = 3.3\text{V}, V_{IN} = V_{IH} \text{ or } V_{IL}, V_O = 1.5\text{V}^{(3)}$		-36	-60	-110	mA
I_{ODL}	Output LOW Current	$V_{CC} = 3.3\text{V}, V_{IN} = V_{IH} \text{ or } V_{IL}, V_O = 1.5\text{V}^{(3)}$		50	90	200	mA
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -0.1\text{mA}$	$V_{CC}-0.2$	—	—	V
			$I_{OH} = -3\text{mA}$	2.4	3	—	
		$V_{CC} = 3\text{V}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -8\text{mA}$	2.4 ⁽⁵⁾	3	—	
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 0.1\text{mA}$	—	—	0.2	V
			$I_{OL} = 16\text{mA}$	—	0.2	0.4	
			$I_{OL} = 24\text{mA}$	—	0.3	0.55	
		$V_{CC} = 3\text{V}$ $V_{IN} = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 24\text{mA}$		0.3	0.5	
I_{OS}	Short Circuit Current ⁽⁴⁾	$V_{CC} = \text{Max.}, V_O = \text{GND}^{(3)}$		-60	-135	-240	mA
V_H	Input Hysteresis	—		—	150	—	mV
I_{CCL} I_{CCH} I_{CCZ}	Quiescent Power Supply Current	$V_{CC} = \text{Max.}$ $V_{IN} = \text{GND or } V_{CC}$		—	0.1	10	μA

3V-8-link

NOTES:

1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at $V_{CC} = 3.3\text{V}$, $+25^{\circ}\text{C}$ ambient.
3. Not more than one output should be tested at one time. Duration of the test should not exceed one second.
4. This parameter is guaranteed but not tested.
5. $V_{OH} = V_{CC} - 0.6\text{V}$ at rated current.

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ΔI_{CC}	Quiescent Power Supply Current	$V_{CC} = \text{Max.}$	$V_{IN} = V_{CC} - 0.6V^{(3)}$	—	2	30	μA
I_{CCD}	Dynamic Power Supply Current ⁽⁴⁾	$V_{CC} = \text{Max.}$ Outputs Open $\overline{OE}_1 = \overline{OE}_2 = \text{GND}$ One Input Toggling 50% Duty Cycle	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	60	85	$\mu A / \text{MHz}$
I_C	Total Power Supply Current ⁽⁶⁾	$V_{CC} = \text{Max.}$ Outputs Open $f_i = 10\text{MHz}$ 50% Duty Cycle $\overline{OE}_1 = \overline{OE}_2 = \text{GND}$ One Bit Toggling	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	0.6	0.9	mA
			$V_{IN} = V_{CC} - 0.6V$ $V_{IN} = \text{GND}$	—	0.6	0.9	
		$V_{CC} = \text{Max.}$ Outputs Open $f_i = 2.5\text{MHz}$ 50% Duty Cycle $\overline{OE}_1 = \overline{OE}_2 = \text{GND}$ Ten Bits Toggling	$V_{IN} = V_{CC}$ $V_{IN} = \text{GND}$	—	1.5	2.1 ⁽⁵⁾	
			$V_{IN} = V_{CC} - 0.6V$ $V_{IN} = \text{GND}$	—	1.5	2.3 ⁽⁵⁾	

NOTES:

- For conditions shown as max. or min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at $V_{CC} = 3.3V$, $+25^\circ C$ ambient.
- Per TTL driven input; all other inputs at V_{CC} or GND .
- This parameter is not directly testable, but is derived for use in Total Power Supply Calculations.
- Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
- $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
 $I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_{CP} N_{CP} / 2 + f_i N_i)$
 $I_{CC} = \text{Quiescent Current (} I_{CCL}, I_{CCH} \text{ and } I_{CCZ})$
 $\Delta I_{CC} = \text{Power Supply Current for a TTL High Input}$
 $D_H = \text{Duty Cycle for TTL Inputs High}$
 $N_T = \text{Number of TTL Inputs at } D_H$
 $I_{CCD} = \text{Dynamic Current Caused by an Input Transition Pair (HLH or LHL)}$
 $f_{CP} = \text{Clock Frequency for Register Devices (Zero for Non-Register Devices)}$
 $N_{CP} = \text{Number of Clock Inputs at } f_{CP}$
 $f_i = \text{Input Frequency}$
 $N_i = \text{Number of Inputs at } f_i$

SWITCHING CHARACTERISTICS OVER OPERATING RANGE⁽³⁾

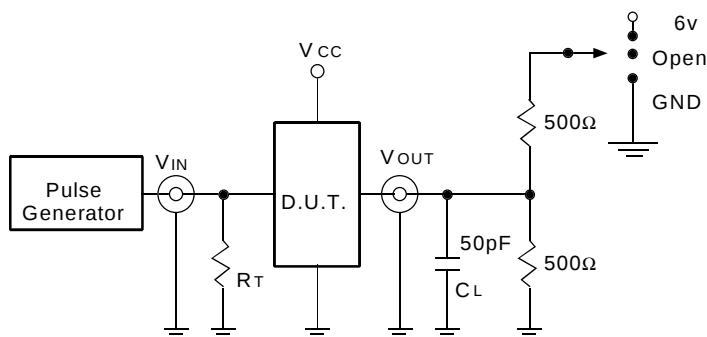
Symbol	Parameter	Condition ⁽¹⁾	FCT3827A		FCT3827B		Unit
			Min. ⁽²⁾	Max.	Min. ⁽²⁾	Max.	
t_{PLH} t_{PHL}	Propagation Delay D_I to Y_i	$C_L = 50\text{pF}$ $R_L = 500\Omega$	1.5	8	1.5	5	ns
		$C_L = 300\text{pF}^{(3)}$ $R_L = 500\Omega$	1.5	15	1.5	13	
t_{PZH} t_{PZL}	Output Enable Time $\overline{OE}_i$ to Y_i	$C_L = 50\text{pF}$ $R_L = 500\Omega$	1.5	12	1.5	8	ns
		$C_L = 300\text{pF}^{(3)}$ $R_L = 500\Omega$	1.5	23	1.5	15	
t_{PHZ} t_{PLZ}	Output Disable Time $\overline{OE}_i$ to Y_i	$C_L = 5\text{pF}^{(3)}$ $R_L = 500\Omega$	1.5	9	1.5	6	ns
		$C_L = 50\text{pF}$ $R_L = 500\Omega$	1.5	10	1.5	7	

NOTES:

- See test circuit and waveforms.
- Minimum limits are guaranteed but not tested on Propagation Delays.
- Propagation Delays and Enable/Disable times are with $V_{CC} = 3.3V \pm 0.3V$, Normal Range. For $V_{CC} = 2.7V$ to $3.6V$, Extended Range, all Propagation Delays and Enable/Disable times should be degraded by 20%.

TEST CIRCUITS AND WAVEFORMS

TEST CIRCUITS FOR ALL OUTPUTS



SWITCH POSITION

Test	Switch
Open Drain Disable Low Enable Low	6V
Disable High Enable High	GND
All Other Tests	Open

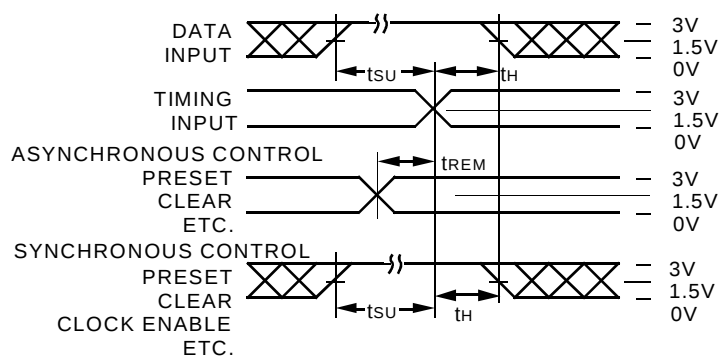
3V-8-link

DEFINITIONS:

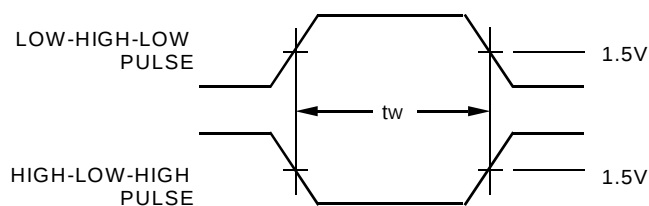
CL = Load capacitance: includes jig and probe capacitance.

RT = Termination resistance: should be equal to ZOUT of the Pulse Generator.

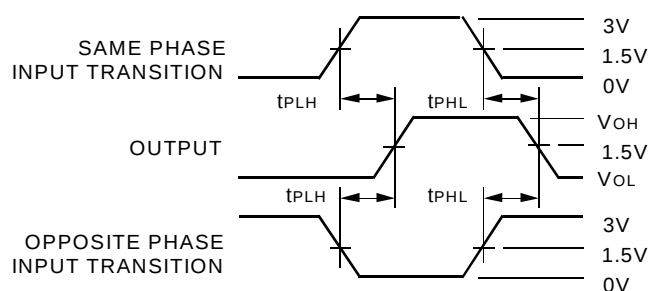
SET-UP, HOLD, AND RELEASE TIMES



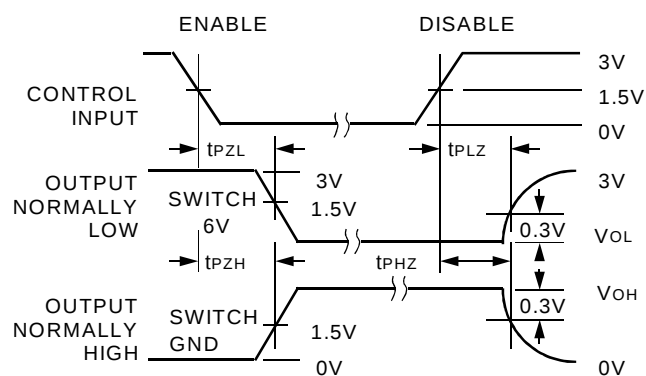
PULSE WIDTH



PROPAGATION DELAY



ENABLE AND DISABLE TIMES



NOTES:

- Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.
- Pulse Generator for All Pulses: Rate $\leq 1.0\text{MHz}$; $t_F \leq 2.5\text{ns}$; $t_R \leq 2.5\text{ns}$.
- If V_{CC} is below 3V, input voltage swings should be adjusted not to exceed V_{CC} .

ORDERING INFORMATION

IDT	XX	FCT	X	XX	X	
Temp. Range			Family	Device Type	Package	
					SO	Small Outline IC (SO24-2)
					Q	Quarter-size Small Outline Package (SO24-8)
				827A		10-Bit Buffer
				827B		
					3	3.3 Volt
					74	- 40°C to +85°C



CORPORATE HEADQUARTERS

2975 Stender Way
Santa Clara, CA 95054

for SALES:

800-345-7015 or 408-727-6116
fax: 408-492-8674
www.idt.com*

*To search for sales office near you, please click the sales button found on our home page or dial the 800# above and press 2.
The IDT logo is a registered trademark of Integrated Device Technology, Inc.